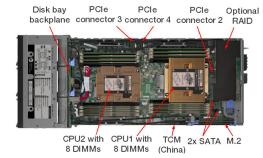
## **ThinkSystem SD530 Platform Specifications**

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Height: 41 mm (1.7 in). Width: 222 mm (8.8 in). Depth: 562 mm (22.2 in)						
ThinkSystem D2 Enclosure. 2U. Up to 4 ThinkSystem SD530 servers per enclosure	ı					
Maximum configuration: 16.6 lb (7.5 kg)						
Path Interconnect) links at maximum 10.4GT/s each						
Intel C624 Platform Controller Hub						
Memory capacity    16 DIMMs models: RDIMMs: Up to 512GB with 16x 32GB RDIMMs and two processors LRDIMMs: Up to 1TB with 16x 64GB LRDIMMs and two processors 12 DIMMs models: RDIMMs: Up to 384GB with 12x 32GB RDIMMs and two processors LRDIMMs: Up to 768GB with 12x 64GB LRDIMMs and two processors						
ECC, Chipkill protection (for x4-based memory DIMMs), memory mirroring, and memory sparing  Supports the following RAID adapters:						
Casha						
Adapter Interface Drive type RAID levels JBOD Cache protection PastPath						
Up to four 2.5" hot-swap disk bays, or up to six 2.5" hot-swap disk bays, or up to six 2.5" hot-swap disk bays with two AnyBay. SAS support requires 530-8i. Optional one or two internal M.2 SSD for boot, dual M.2 SSD supports mirroring						
2.5" HDD, SATA6Gbps, 7,2K     1TB/2TB       2.5" HDD, SAS12Gbps, 7,2K     2TB						
	H					
	Н					
	П					
2.5" SSD, SATA6Gbps 240GB/480GB/960GB/1.92TB/3.84TB	Ш					
2.5" SSD, SAS12Gbps 400GB/800GB/1.6TB/3.84TB/7.68TB/15.36TB	Ш					
Two 10 GbE ports, SFP+ or RJ-45, routed through the Ethernet I/O Module at the rear of the D2 Enclosure. Networking ports are based on Intel Ethernet Connection X722 in chipset						
Power-on and admin password. Trusted Platform Module, TCG 1.2 and 2.0						
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Operator panel with system error LED and ID and power controls. XClarity Controller embedded management, XClarity Administrator centralized infrastructure delivery, XClarity Integrator plugins, and XClarity Energy Manager centralized server power management.  Optional XClarity Controller Advanced to enable remote control functions.						
temsmanagement functions						
None						
MT 7X21: 3-year limited onsite service with 9x5/NBD						
Supplied by D2 Enclosure						
Integrated Matrox G200 in XClarity Controller						
Optional KVM breakout module for one USB 3.0 and one console breakout cable port for local KVM and serial ports.  KVM breakout module will ocuppy one disk bay on 6x 2.5" disk bay model						
	ThinkSystem D2 Enclosure. 2U. Up to 4 ThinkSystem SD530 servers per enclosure Maximum configuration: 16.6 lb (7.5 kg) Up to two 165W Intel Xeon Scalable family processors, Bronze, Silver, Gold, or Platinum. Up to 28 cores at 2.1GHz, up to 3.6GHz with 4 cores. Up to two UPI (Ultra Path Interconnect) links at maximum 10.4GT/s each Intel C624 Platform Controller Hub Up to 12 or 16 DIMM sockets depending on the processor selected. Each processor supports up to 6 or 8 DIMM sockets. DDR4-2666. RDIMMs and LRDIMMs are supported, but memory types cannot be intermixed.  16 DIMMs models: RDIMMs: Up to 512GB with 16x 32GB RDIMMs and two processors LRDIMMs: Up to 171B with 16x 64GB LRDIMMs and two processors LRDIMMs: Up to 384GB with 12x 32GB RDIMMs and two processors LRDIMMs: Up to 768GB with 12x 32GB RDIMMs and two processors ECC, Chipkill protection (for x4-based memory DIMMs), memory mirroring, and memory sparing  Supports the following RAID adapters:  Adapter Interface Drive type RAID levels BDOD Cache Cache Control of the Control of					

Componen	ts Specification				
	Supports ASHRAE	A4 with limitations.			
 e	Temperature - operating	A4: 5°C to 45°C (41°F to 113°F)   A3: 5°C to 40°C (41°F to 104°F)   A2: 10°C to 35°C (50°F to 95°F)			
<b>-</b>	Temperature - non operatii	g (no package) -10°C to 60°C (14°F to 140°F)			
Environmer	tal Temperature - non operatii	g (with package) -40°C to 70°C (-40°F to 158°F)			
specification	Altitude - operating	(Unpressurized): 0-10000ft (0-3048m)			
a∥ '	Humidity - operating, non-	ondensing A4: 8%~90%. A3:8%~85%. A2:20%~80%			
	Humidity - storage (with pa	ckage), non-condensing 8%~90%			
or	<ul> <li>NVMe drives not installed</li> </ul>	Models should meet the following requirements to support A3 and A4:  NVMe drives not installed  M.2 drives not installed			

Expansion slots
Supports one PCle 3.0 x16 low-profile slot, or two PCle 3.0 x8 low-profile slots.
Slots are housed in I/O shuttle in rear of the D2 Enclosure



## Backplane and memory DIMM sockets supports by processor

Maxium DIMM Sockets	xium DIMM Sockets 12 DIMMs		16 DIMMs		
Backplane	2x2	2x3	2x2	2x3	
Xeon Bronze 3104	Yes	Yes	Yes	No	
Xeon Bronze 3106	Yes	Yes	Yes	No	
Xeon Silver 4108	Yes	Yes	Yes	No	
Xeon Silver 4109T	Yes	No	No	No	
Xeon Silver 4110	Yes	Yes	Yes	No	
Xeon Silver 4112	Yes	Yes	Yes	No	
Xeon Silver 4114	Yes	Yes	Yes	No	
Xeon Silver 4116	Yes	Yes	Yes	No	
Xeon Gold 5115	Yes	Yes	Yes	No	
Xeon Gold 5118	Yes	Yes	Yes	No	
Xeon Gold 5120	Yes	Yes	Yes	No	
Xeon Gold 5120T	Yes	No	No	No	
Xeon Gold 5122	Yes	No	No	No	
Xeon Gold 6126	Yes	Yes	No	No	
Xeon Gold 6130	Yes	Yes	Yes	No	
Xeon Gold 6130T	Yes	No	No	No	
Xeon Gold 6134	Yes	No	No	No	
Xeon Gold 6136	Yes	No	No	No	
Xeon Gold 6138	Yes	Yes	No	No	
Xeon Gold 6138T	Yes	No	No	No	
Xeon Gold 6140	Yes	Yes	No	No	
Xeon Gold 6142	Yes	No	No	No	
Xeon Gold 6148	Yes	No	No	No	
Xeon Gold 6150	Yes	No	No	No	
Xeon Gold 6152	Yes	Yes	No	No	
Xeon Platinum 8153	Yes	Yes	Yes	No	
Xeon Platinum 8156	Yes	No	No	No	
Xeon Platinum 8158	Yes	No	No	No	
Xeon Platinum 8160	Yes	No	No	No	
Xeon Platinum 8164	Yes	No	No	No	
Xeon Platinum 8170	Yes	No	No	No	
Xeon Platinum 8176	Yes	No	No	No	